



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-07-30
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	B9YE*FS61BBQ	A	1054	2018-07-30
Amount	UoM	Unit type	ST ECOPACK Grade	
520.00	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	NiPdAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape
QFP	14-14-1	100	gull wing
Comment	Package: TQFP 100 14x14x1.0 1.0 ExpadDown - MDF valid for CPs: SPC574S64E3CEFAY - SPC574S64E3CEFAR		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.68	Die - Leadframe	3235

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	89YE*F5618BQ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	24.194	mg	supplier	die	Silicon (Si)	7440-21-3		23.437	mg	968713	45073
				supplier	metallization	Aluminium (Al)	7429-90-5		0.053	mg	2191	102
				supplier	metallization	Copper (Cu)	7440-50-8		0.317	mg	13102	610
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	40	2
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.052	mg	2149	100
				supplier	metallization	Titanium (Ti)	7440-32-6		0.014	mg	579	27
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	83	4
				supplier	Passivation	Silicon Nitride	12033-89-5		0.072	mg	2976	138
				supplier	Passivation	Silicon Oxide	7631-86-9		0.246	mg	10167	473
				Leadframe	M-004 Copper and its alloys	220.335	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.219	mg	994	421
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.066	mg	300	124
supplier	metallization	Nickel (Ni)	7440-02-0						1.681	mg	7629	3233
supplier	metallization	Palladium (Pd)	7440-05-3						0.108	mg	490	208
supplier	metallization	Gold (Au)	7440-57-5						0.045	mg	204	87
supplier	glue	Silver (Ag)	7440-22-4						5.374	mg	895070	10335
supplier	glue	Isobornyl Methacrylate	7534-94-3						0.450	mg	74950	865
supplier	glue	Bismaleimide resin	Proprietary						0.180	mg	29980	346
Bonding wires	M-011 Other inorganic materials	0.922	mg					supplier	wire	Copper (Cu)	7440-50-8	
Encapsulation	M-011 Other inorganic materials	268.545	mg	supplier	mold compound	Silica, vitreous	60676-86-0		232.022	mg	863997	446196
				supplier	mold compound	Epoxy Resin	25068-38-6		20.141	mg	75000	38733
				supplier	mold compound	Phenol Resin	29690-82-2		13.427	mg	49999	25821
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		1.343	mg	5001	2583
				supplier	mold compound	Quartz	14808-60-7		0.806	mg	3002	1550
				supplier	mold compound	Carbon black	1333-86-4		0.806	mg	3001	1550